

## In the Claims:

Please rewrite Claim 1 and add new Claims 6-12 as follows:

1. (Currently Amended) A card connector assembly insertable into and extractable from an apparatus containing a circuit, the card connector assembly comprising:

a substrate on which wiring traces are formed and an electrical component is mounted;

a plurality of contact lands connected to the respective wiring traces and arranged along an edge of the substrate such that the contact lands are connected to the circuit when the card connector assembly is inserted into the apparatus;

connecting traces that interconnect the respective contact lands and the respective wiring traces; and

lands on the respective connecting traces, each land having a contact area for a test pin.

2. (Original) A card connector assembly according to Claim 1, wherein each land corresponds to each of the plurality of contact lands, and at least some of the lands have a width greater than that of the corresponding connecting trace.

3. (Original) A card connector assembly according to Claim 1, wherein each land is disposed in the vicinity of the corresponding contact land.

4. (Original) A card connector assembly according to Claim 1, wherein the plurality of lands are arranged in a line.

5. (Original) A card connector assembly according to Claim 1, further comprising a housing that covers the substrate including the lands but does not cover the plurality of contact lands.

6. (New) A method of protecting contact lands of a card connector assembly during testing, the method comprising:

providing a substrate containing wiring traces, contact lands connected to the wiring traces via connecting traces, test lands on the connecting traces, and an electrical component, the contact lands arranged along an edge of the substrate and the test lands having contact areas; and

evaluating electrical performance of the card connector using contact between at least one of the contact areas and a test pin prior to the card connector being inserted into an apparatus containing a circuit and the contact lands making electrical contact with the circuit.

7. (New) The method according to Claim 6, further comprising inserting the card connector into the apparatus such that the contact lands make electrical contact with the circuit.

8. (New) The method according to Claim 6, wherein each of the plurality of contact lands has a corresponding test land.

9. (New) The method according to Claim 8, wherein at least some of the lands have a width greater than that of the corresponding connecting trace.

10. (New) The method according to Claim 8, wherein each test land is disposed in the vicinity of the corresponding contact land.

11. (New) The method according to Claim 6, wherein the plurality of test lands is arranged in a line.

12. (New) The method according to Claim 6, further comprising covering a portion of the substrate that includes the test lands without covering the contact lands after evaluating the electrical performance of the card connector.